

Supplementary

# Solid-Liquid Interdiffusion (SLID) Bonding of p-Type Skutterudite Thermoelectric Material Using Al-Ni Interlayers

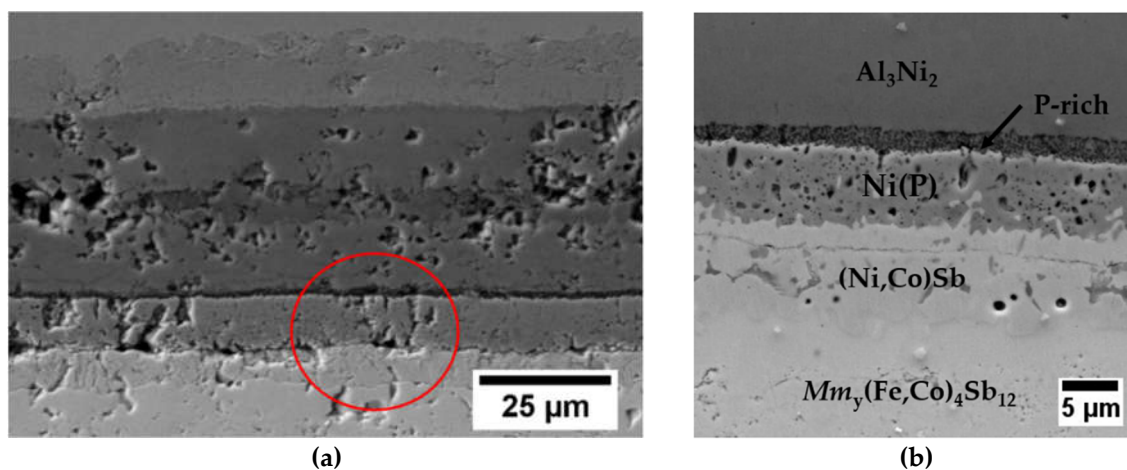
Katarzyna Placha <sup>1,2,\*</sup>, Richard S. Tuley <sup>1</sup>, Milena Salvo <sup>2</sup>, Valentina Casalegno <sup>2</sup> and Kevin Simpson <sup>1</sup>

<sup>1</sup> European Thermodynamics Ltd., 8 Priory Business Park, Leicester, LE8 0RX, UK; richard.tuley@etdyn.com (R.S.T.); kevin@etdyn.com (K.S.)

<sup>2</sup> Politecnico di Torino, Department of Applied Science and Technology, Corso Duca degli Abruzzi, 10129, Turin, Italy; milena.salvo@polito.it (M.S.); valentina.casalegno@polito.it (V.C.)

\* Correspondence: katarzyna@etdyn.com; Tel.: +44-7922-810-492

Received: 30 October 2018; Accepted: 4 December 2018; Published: 6 December 2018



**Figure S1.** (a) Cross-sectional microstructure of the skutterudite–interconnect interfaces bonded at 660 °C and isothermally aged at 450 °C for 96 h, under flowing Ar; (b) red circle presents the enlarged area shown in (a) with a high magnification Scanning electron microscope (SEM) image of the Ni(P)–Al<sub>3</sub>Ni<sub>2</sub> interface.